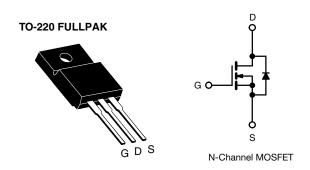
Vishay Siliconix

COMPLIANT

HALOGEN

FREE

E Series Power MOSFET



PRODUCT SUMMARY			
V _{DS} (V) at T _J max.	650)	
R _{DS(on)} max. (Ω) at 25 °C	V _{GS} = 10 V	0.28	
Q _g max. (nC)	78		
Q _{gs} (nC)	9		
Q _{gd} (nC)	17		
Configuration	Sing	le	

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220 FULLPAK
Lead (Pb)-free	SiHF15N60E-E3
Lead (Pb)-free and Halogen-free	SiHF15N60E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unle	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V _{DS}	600	V
Gate-Source Voltage			V_{GS}	± 30	V
Continuous Drain Current (T _J = 150 °C) ^e	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	l-	15	
Continuous Drain Current (1) = 150 C)	VGS at 10 V	T _C = 100 °C	I _D	9.6	Α
Pulsed Drain Current ^a			I _{DM}	39	
Linear Derating Factor				0.27	W/°C
Single Pulse Avalanche Energy b	Single Pulse Avalanche Energy b			102	mJ
Maximum Power Dissipation			P_{D}	34	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope	$V_{DS} = 0 V to$	o 80 % V _{DS}	dV/dt	70	V/ns
Reverse Diode dV/dt ^d			av/at	7.7	V/IIS
Soldering Recommendations (Peak temperature) c	For '	10 s		300	°C
Mounting Torque	M3 s	crew		0.6	Nm

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 11.6 mH, R_g = 25 Ω , I_{AS} = 4.2 A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$.
- e. Limited by maximum junction temperature.



Vishay Siliconix

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	-	65	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	3.7	C/ VV

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static				•	•		
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 250 μA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.71	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2	-	4	V
Coto Course Legisone			$V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
Gate-Source Leakage	I_{GSS}		$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zone Ooto Voltana Dusia Ormant		V _{DS} =	= 600 V, V _{GS} = 0 V	-	-	1	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 8 A	-	0.23	0.28	Ω
Forward Transconductance	9 _{fs}	V _{DS}	s = 30 V, I _D = 8 A	-	4.6	-	S
Dynamic				•	•		
Input Capacitance	C _{iss}		$V_{GS} = 0 V$		1350		
Output Capacitance	C _{oss}		$V_{DS} = 100 \text{ V},$	-	70	-	1
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz		5	-	pF
Effective Output Capacitance, Energy Related ^a	$C_{o(er)}$			-	53	-	
Effective Output Capacitance, Time Related ^b	C _{o(tr)}	V _{DS} = 0 \	$/$ to 480 V, $V_{GS} = 0 V$	-	177	-	
Total Gate Charge	Qg			-	39	78	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 8 A, V_{DS} = 480 V$	-	11	-	nC
Gate-Drain Charge	Q _{gd}			-	17	-	
Turn-On Delay Time	t _{d(on)}			-	16	32	
Rise Time	t _r	$V_{DD} = 480 \text{ V}, I_{D} = 8 \text{ A},$		-	26	52	ns
Turn-Off Delay Time	t _{d(off)}		$V_{DD} = 480 \text{ V}, I_D = 8 \text{ A},$ $V_{GS} = 10 \text{ V}, R_q = 9.1 \Omega$		41	82	
Fall Time	t _f		Ů	_	22	44	1
Gate Input Resistance	R_g	f = 1 MHz, open drain		0.3	0.86	1.7	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	bol	-	-	15	
Pulsed Diode Forward Current	I _{SM}	integral revers p - n junction		-	-	60	A
Diode Forward Voltage	V _{SD}	T _J = 25 °	C, I _S = 8 A, V _{GS} = 0 V	-	1.0	1.2	V
Reverse Recovery Time	t _{rr}			-	302	604	ns
Reverse Recovery Charge	Q _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 8 \text{ A},$ $dI/dt = 100 \text{ A/}\mu\text{s}, V_R = 25 \text{ V}$		-	4.0	8	μC
Reverse Recovery Current	I _{RRM}			-	24	-	Α

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

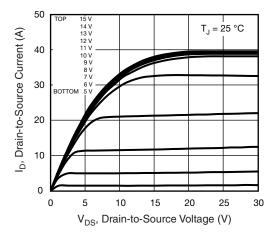


Fig. 1 - Typical Output Characteristics

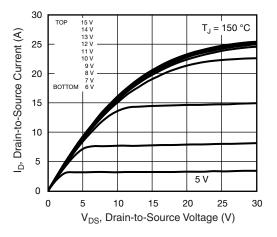


Fig. 2 - Typical Output Characteristics

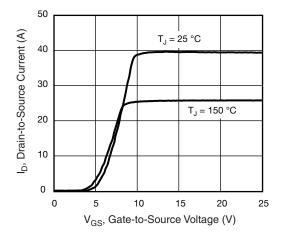


Fig. 3 - Typical Transfer Characteristics

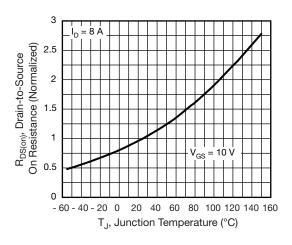


Fig. 4 - Normalized On-Resistance vs. Temperature

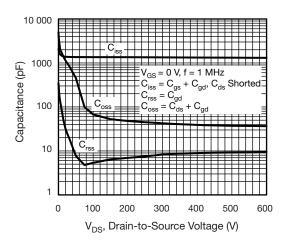


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

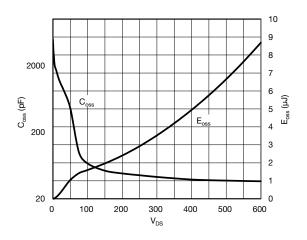


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



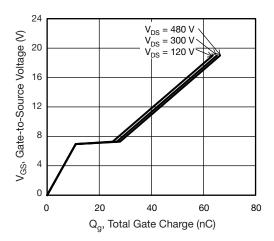


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

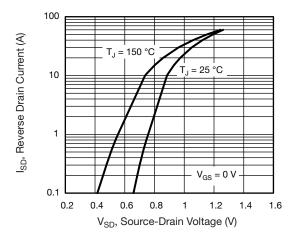


Fig. 8 - Typical Source-Drain Diode Forward Voltage

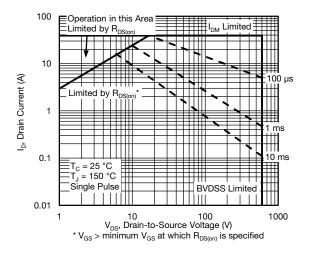


Fig. 9 - Maximum Safe Operating Area

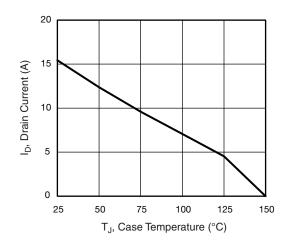


Fig. 10 - Maximum Drain Current vs. Case Temperature

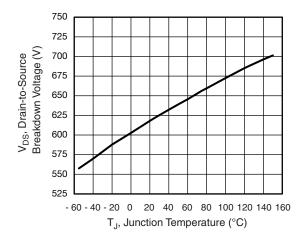


Fig. 11 - Temperature vs. Drain-to-Source Voltage



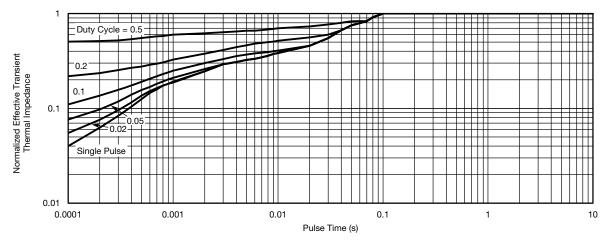


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

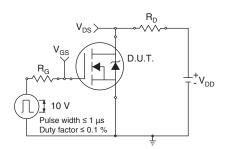


Fig. 13 - Switching Time Test Circuit

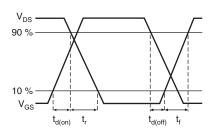


Fig. 14 - Switching Time Waveforms

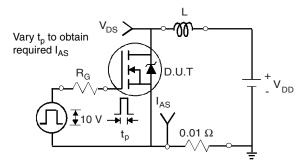


Fig. 15 - Unclamped Inductive Test Circuit

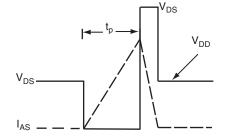


Fig. 16 - Unclamped Inductive Waveforms

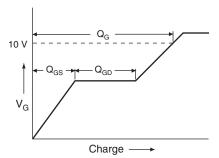


Fig. 17 - Basic Gate Charge Waveform

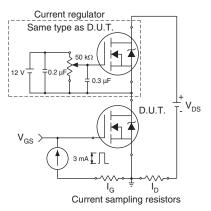
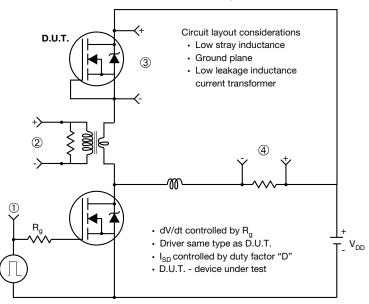


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



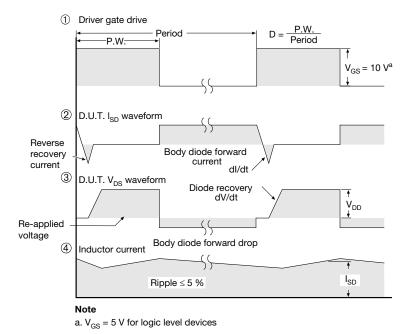


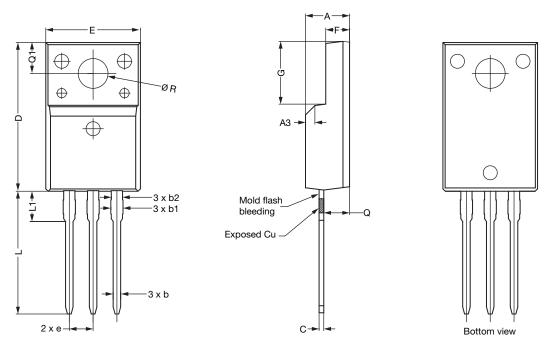
Fig. 19 - For N-Channel

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Vishay Siliconix

TO-220 FULLPAK (High Voltage)

OPTION 1: FACILITY CODE = 9

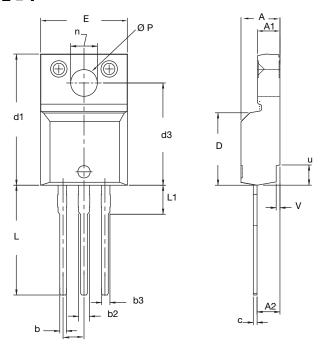


		MILLIMETERS	
DIM.	MIN.	NOM.	MAX.
A	4.60	4.70	4.80
b	0.70	0.80	0.91
b1	1.20	1.30	1.47
b2	1.10	1.20	1.30
С	0.45	0.50	0.63
D	15.80	15.87	15.97
е		2.54 BSC	
E	10.00	10.10	10.30
F	2.44	2.54	2.64
G	6.50	6.70	6.90
L	12.90	13.10	13.30
L1	3.13	3.23	3.33
Q	2.65	2.75	2.85
Q1	3.20	3.30	3.40
ØR	3.08	3.18	3.28

- 1. To be used only for process drawing
- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
- 5. No chipping or package damage
- 6. Facility code will be the 1st character located at the 2nd row of the unit marking



OPTION 2: FACILITY CODE = Y



	MILLIM	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
E	10.360	10.630	0.408	0.419	
е	2.54	BSC	0.100 BSC		
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØP	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	

ECN: E19-0180-Rev. D, 08-Apr-2019

DWG: 5972

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- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
- 5. No chipping or package damage
- 6. Facility code will be the 1st character located at the 2nd row of the unit marking



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Vishay

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